U.S. Department of Commerce, Patent and Trademark Office	Application No.:	09/974,571
	Filing Date:	October 9, 2001
	First Named Inventor:	Peter G. Borden
	Group Art Unit:	2877
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Examiner Name:	Unknown
(Use several sheets if necessary)	Confirmation No.:	1003
	Attorney Docket No.:	BOX013 US

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*Examiner Intials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
PAD	1.	4,273,421	6/16/81	Gurtler	356	432	
PD	2.	4,854,710	8/8/89	Opsal et al.	356	432	
PD	3.	4,211,488	7/8/80	Kleinknecht	356	433	
PD	4.	5,379,109	1/3/95	Gaskill et al.	356	445	
PD	5.	6,489,801	12/3/02	Borden et al.	324	766	
PD	6.	5,966,019	10/12/99	Borden	324	752	
PAD	7.	5,377,006	12/27/94	Nakata	356	349	
PD	8.	5,706,094	1/6/98	Maris	356	432	
PD	9.	6,118,533	9/12/00	Banet et al.	356	345	
PD	10.	6,323,951	11/27/01	Borden et al.	356	502	
PD	11.	6,426,644	7/30/02	Borden et al.	324	765	
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PD	16.	5,228,776	7/20/93	Smith et al.	374	5	
PD	17.	4,255,971	3/17/81	Rosencwaig	73	606	
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PD	20.	4,636,088	1/13/87	Rosencwaig et al.	374	5	
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PD	22.	4,513,384	4/23/95	Rosencwaig	364	563	
PD	23.	6,049,220	4/11/00	Borden et al.	324	765	
PD	24.	6,483,594	11/19/02	Borden et al.	356	502	
PD	25.	5,652,716	7/29/97	Battersby	703	13	

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	26	5,761,082	6/2/98	Miura-Mattausch	703	14	
	27	4,996,659	2/26/91	Yamaguchi et al.	714	736	
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	44	6,281,027	9/28/01	Wei et al.	438	14	
	45	4,521,118	06/00/85	Rosencwaig	374	5	
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	50	4,552,510	6/11/85	Rosencwaig	374	7	
	51	4,571,685	02/18/86	Kamoshida	364	468	

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(Use several sheets if necessary)

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							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
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U.S. Patent Documents

*Examiner Intials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
[illegible]	1.	2001/0015937	8/23/01	Yamaguchi et al.	369	13	
[illegible]	2.	6,020,964	2/1/00	Loopstra et al.	356	500	
[illegible]	3.	6,400,454	6/4/02	Noguchi et al.	356	237	

Foreign Patent Documents

							Translation	
		Document	Date	Country	Class	Subclass	Yes	No

Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)

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